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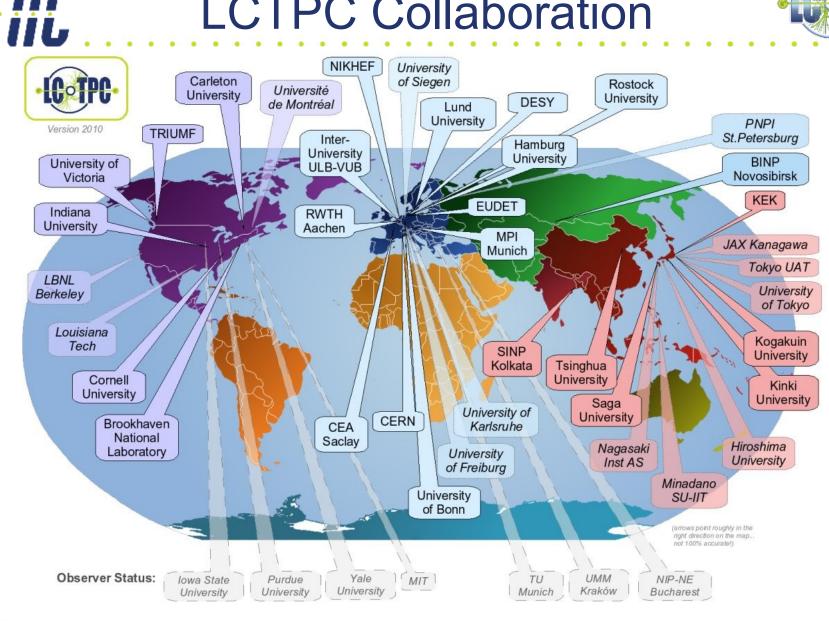


Large TPC Prototype of LCTPC

Klaus Dehmelt DESY On behalf of the LCTPC Collaboration *LCWS2010* Beijing, China March 27, 2010

LCTPC Collaboration









Performance goals and design parameters for a TPC with standard electronics at the ILC detector

Size	$\phi = 3.6 \text{m}, \text{L} = 4.3 \text{m}$ outside dimensions
Momentum resolution $(3.5T)$	$\delta(1/p_t)\sim 9\times 10^{-5}/{\rm GeV/c}$ TPC only (\times 0.4 if IP incl.)
Momentum resolution $(3.5T)$	$\delta(1/p_t) \sim 2 \times 10^{-5}/\text{GeV/c} \text{ (SET+TPC+SIT+VTX)}$
Solid angle coverage	Up to $\cos\theta \simeq 0.98$ (10 pad rows)
TPC material budget	$\sim 0.04 X_0$ to outer fieldcage in r
($\sim 0.15 X_0$ for readout endcaps in z
Number of pads/timebuckets	$\sim 1 \times 10^6/1000~{\rm per}$ endcap
Pad size/no.padrows	\sim 1mm ×4–6mm/~200 (standard readout)
σ_{point} in $r\phi$	$< 100 \mu m$ (average over L _{sensitive} , modulo track ϕ angle)
σ_{point} in rz	$\sim 0.5 \text{ mm} (\text{module track } \theta \text{ angle})$
2-hit resolution in $r\phi$	$\sim 2 \text{ mm} \pmod{\text{track angles}}$ with MPGD
2-hit resolution in rz	$\sim 6 \text{ mm} (\text{modulo track angles})$
dE/dx resolution	$\sim 5\%$
Performance	$>97\%$ efficiency for TPC only (p_t > 1 GeV/c), and
	$> 99\%$ all tracking (p _t $> 1 \mathrm{GeV/c})$
Background robustness	Full efficiency with 1% occupancy
Background safety factor	Chamber will be prepared for 10 \times worse backgrounds
	at the linear collider start-up

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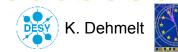
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- Design, build and operate a "Large Prototype" (LP)
- First iterations of LCTPC design details can be tested
- Larger area readout can be operated
- Tracks with a large number of measured points are available \rightarrow analysis and correction procedures

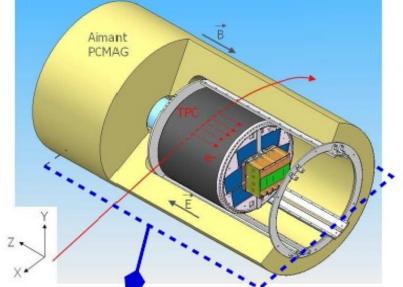


DESY Test Beam Setup

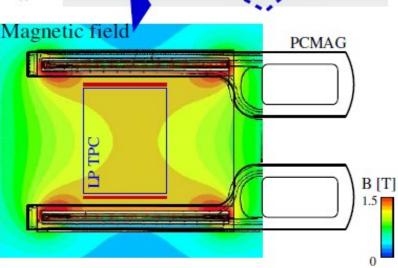


EUDET setup for TPC R&D

- PCMAG with $B \leq 1.25 \,\mathrm{T}$
- ullet bore diameter: 85 cm
- LP support structure
- Test Beam e^- with $1 \, {
 m GeV} \le E_{\sf beam} \le 6 \, {
 m GeV}$







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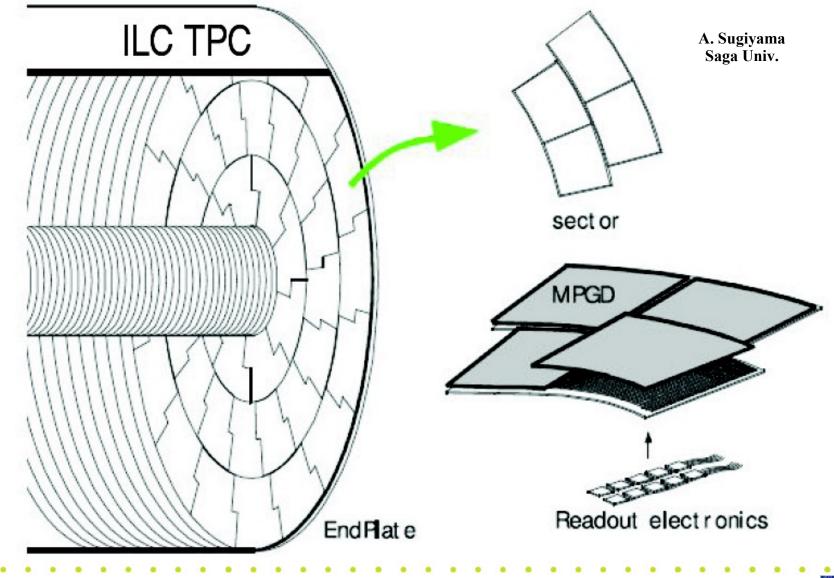
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TPC with MPGD





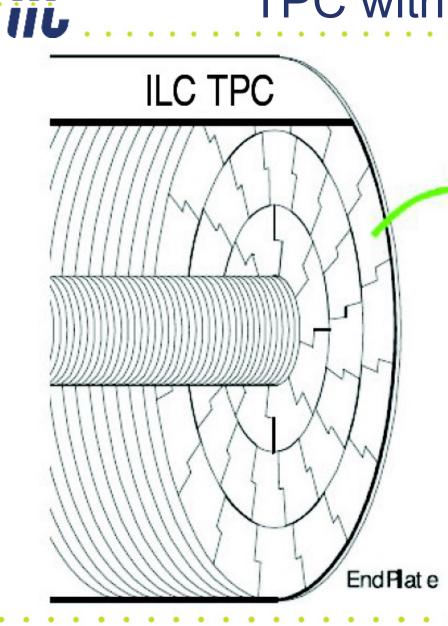
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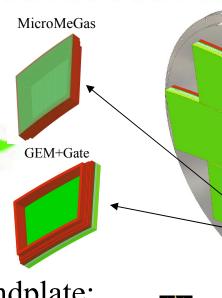
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TPC with MPGD







Endplate:



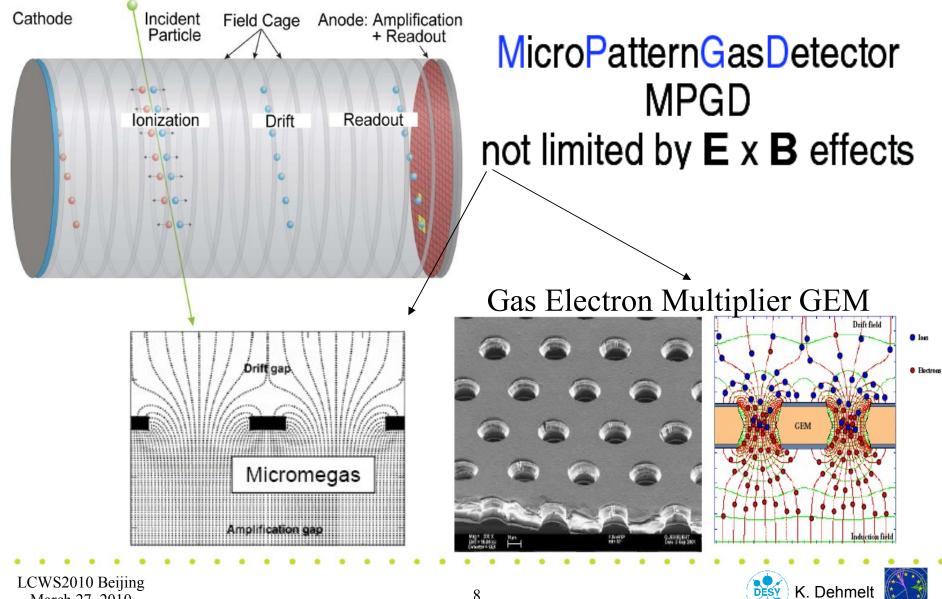
D. Peterson, Cornell

K. Dehmelt

- Aluminum
- Accommodates seven detector/ dummy modules
- $d = d_{outer,FC} = 770 \text{ mm}$
- Modules have same shape \rightarrow interchangeable

TPC with MPGD





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LP-TPC Field Cage (FC)

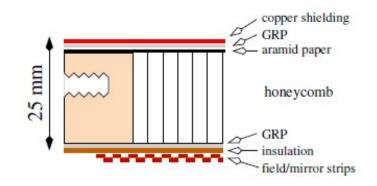


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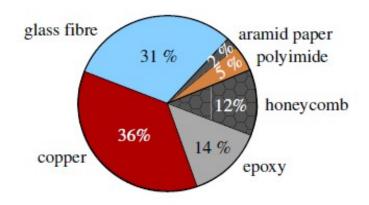
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Diameter: Inner 720 mm, Outer 770 mm → wall thickness 25 mm Length 610 mm HV to be applied: up to 20 kV \rightarrow structure made from composite materials



 \rightarrow material budget: 1.24 % X₀



 $\Rightarrow 1\,\%\,\mathrm{X}_0$ per wall within reach

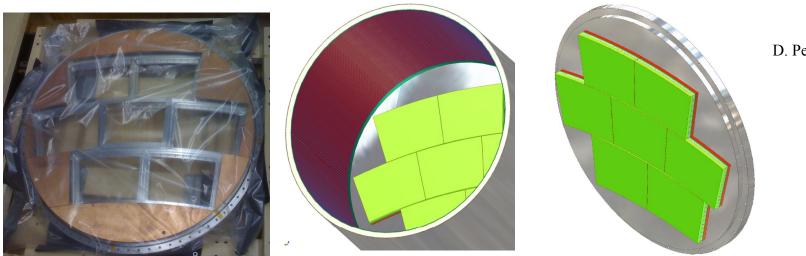




LP-TPC Endplate







D. Peterson, Cornell



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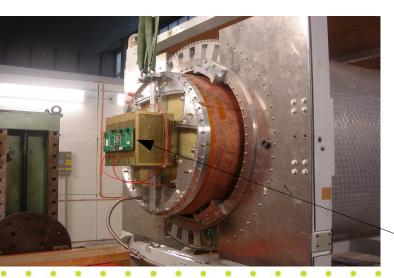


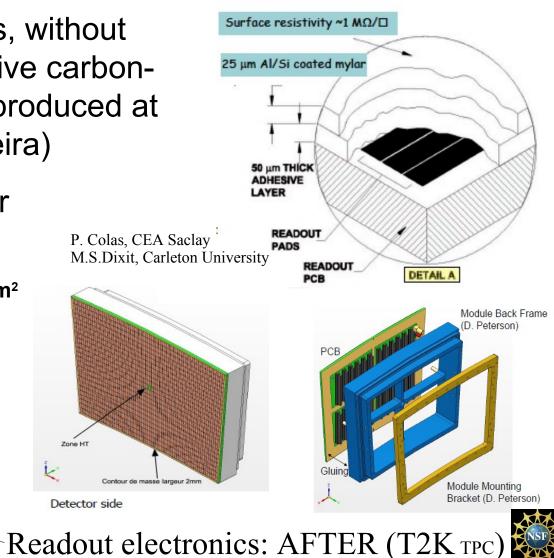




'Bulk Micromegas' panels, without resistive foil and with resistive carbonloaded kapton, have been produced at CERN (Rui de Oliveira)

MicroMeGas for LP: 24 rows x 72 pads Av. Pad size: 3.2 x 7mm²







K. Dehmelt

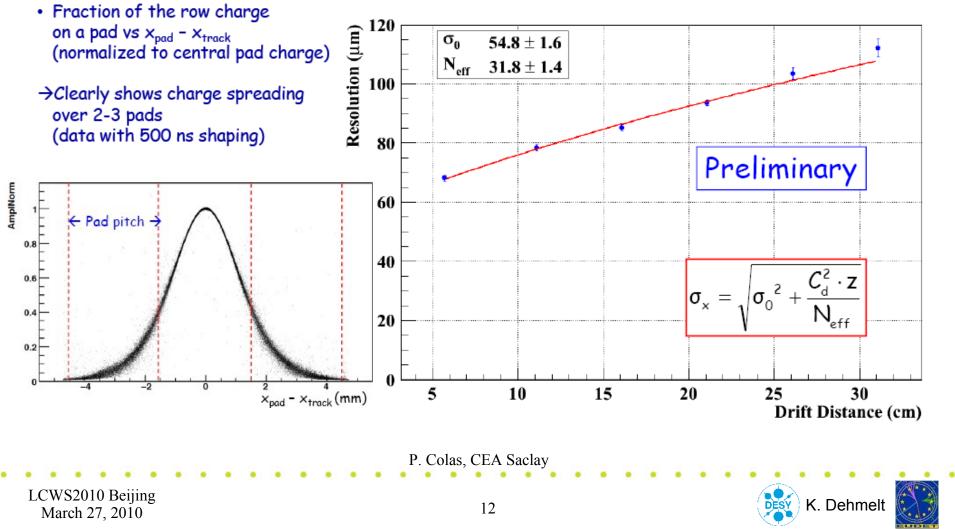


Electrons (5 GeV), Magnetic field (B=1T)

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• Resolution at z=0: σ_{0} = 54.8±1.6 μm with 2.7–3.2 mm pads (w_{pad}/55)

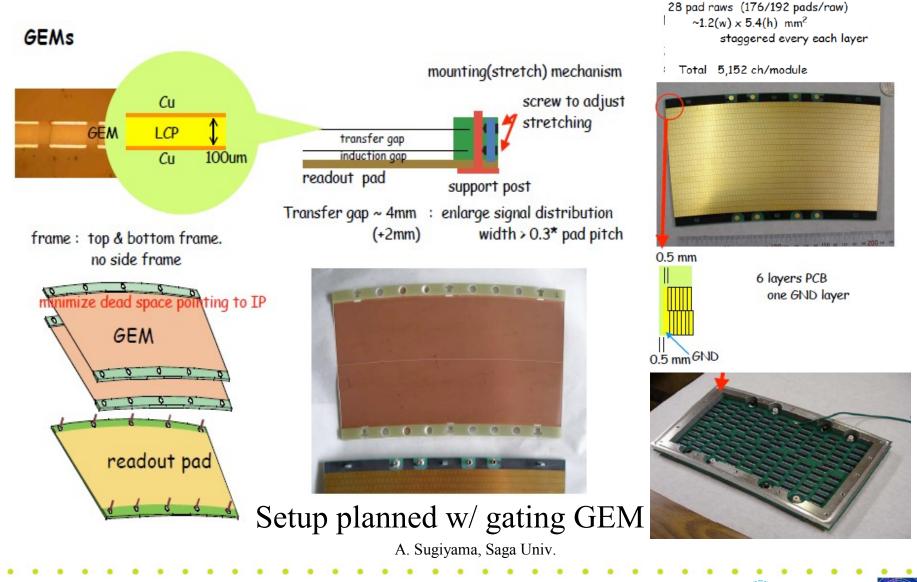
Effective number of electrons: N_{eff} = 31.8±1.4 consistent with expectations



MicroMeGaS Structure

Double GEM Structure





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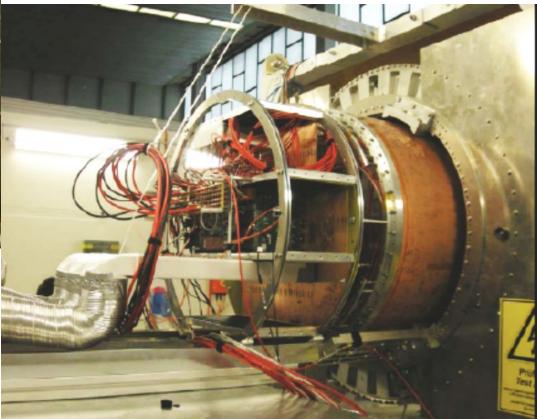
Double GEM Structure

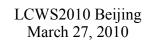




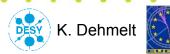
Readout electronics: Based on ALTRO (ALICE TPC) L. Joensson, LUND University

About 3200 channels readout electronics



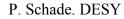


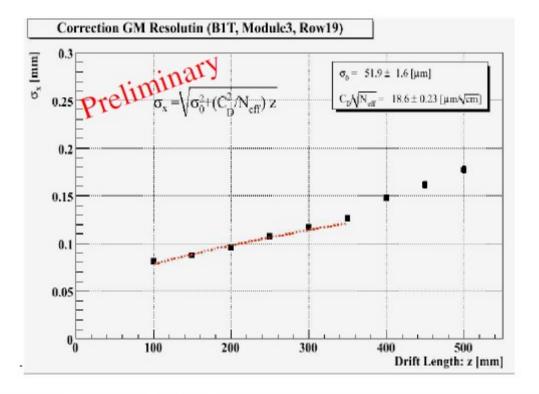
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Double GEM Structure







First Results (GEM modules)

• res. parametrized as
$$\sigma_{\perp} = \sqrt{\sigma_0^2 + D^2/N_{\text{eff}} \cdot z}$$

 $\rightarrow D/\sqrt{N_{\text{eff}}} = 18.5 \pm 0.2 \,\mu\text{m}/\sqrt{\text{cm}} - \sigma_0 = 51.9 \pm 1.6 \,\mu\text{m}$

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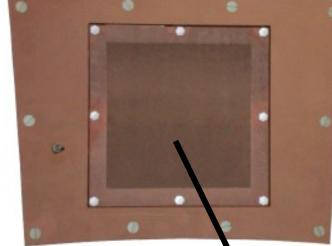
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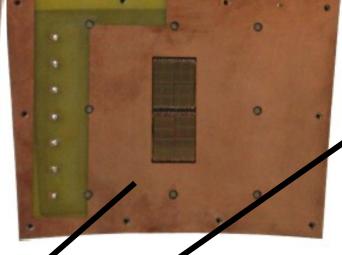


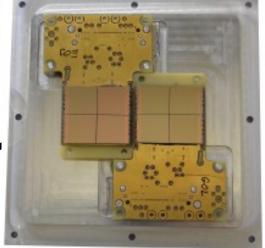












anode plane

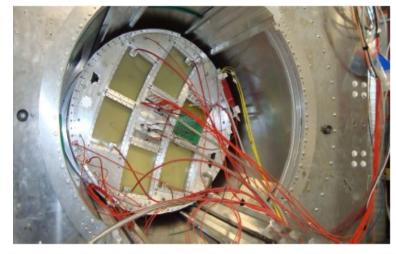
GEMs

readout plane

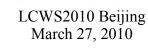
quad-boards reinforcement of anode plane

redframe

Readout: 2 quadboards (4 TimePix chips, 1.4 x 1.4 cm² each) J. Kaminski, Univ. of Bonn



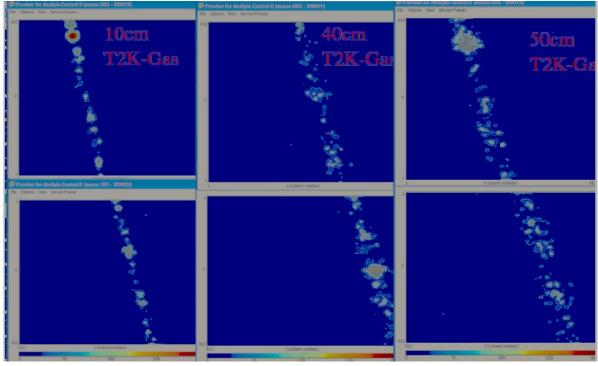
K. Dehmelt

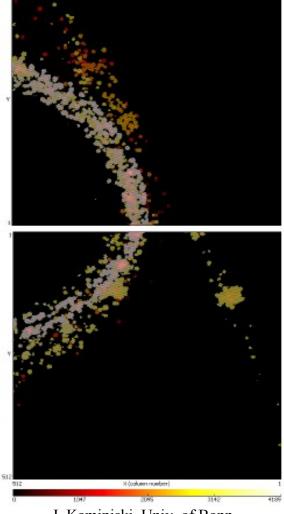


3-GEM Structure & TimePix

Largest amount of readout channels on one TPC anode so far: # ch \cong 500 k

- Single cluster detection
- Clear identification of δ -electrons
- Cluster counting \rightarrow improve dE/dx measurement
- Analysis ongoing





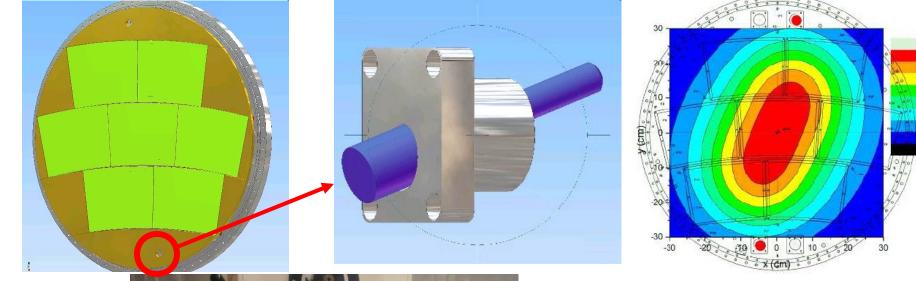




Laser Calibration Setup

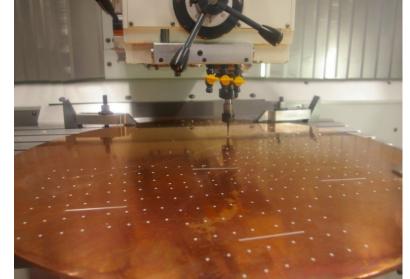


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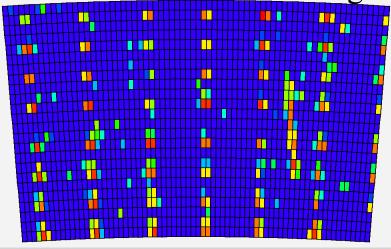


P. Conley Victoria Univ.

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Pattern seen with Micromegas

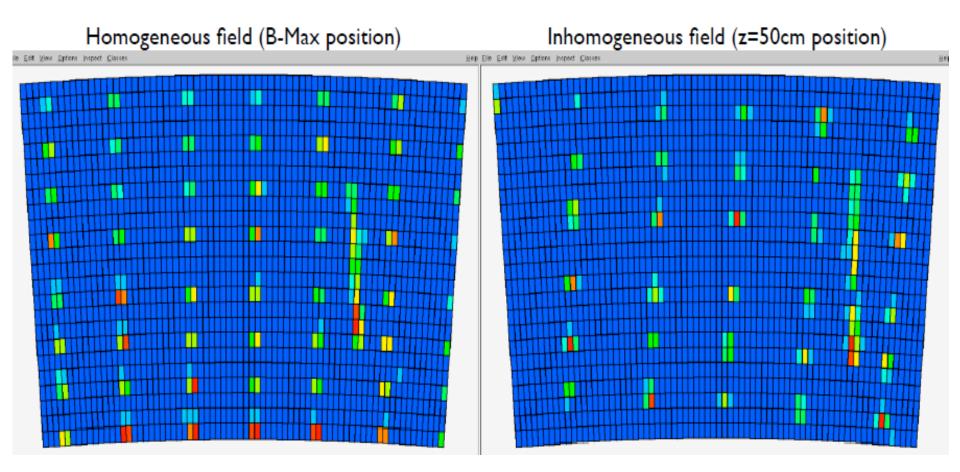






P. Conley Victoria Univ.

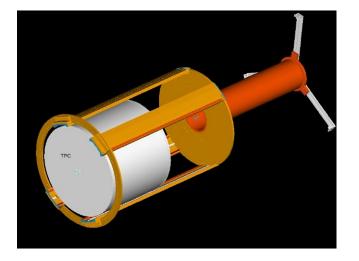
Distortions seen with MicroMegas module

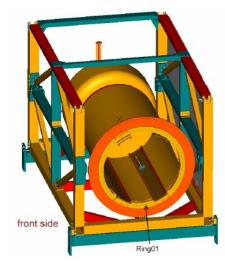




LP Mechanics







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Design Study of the Magnetmovementtable

Support structures:

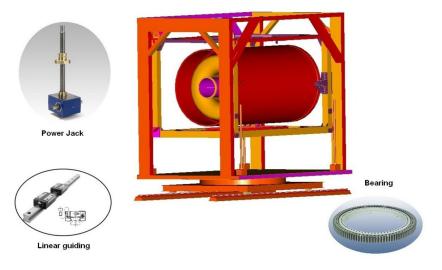
• TPC

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- PCMAG
- F. Hegner, V. Prahl, R. Volkenborn, DESY





LP Mechanics



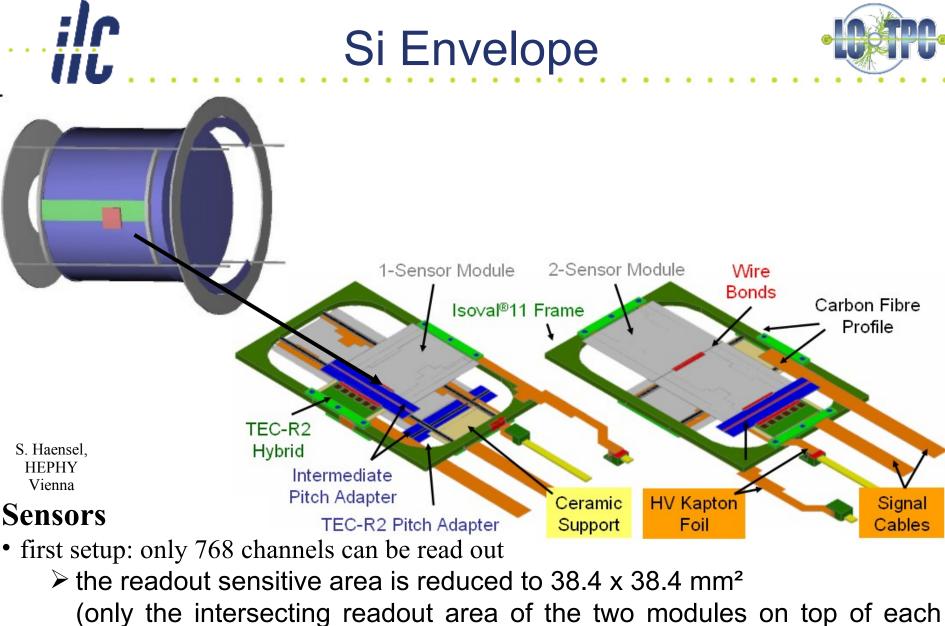


Actuation and Control





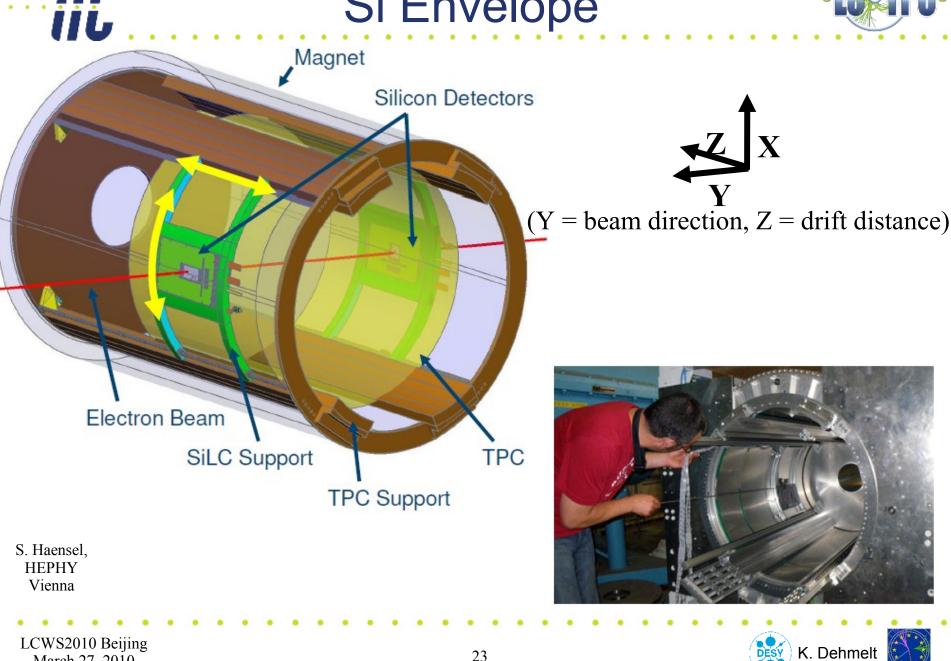




other is interesting)

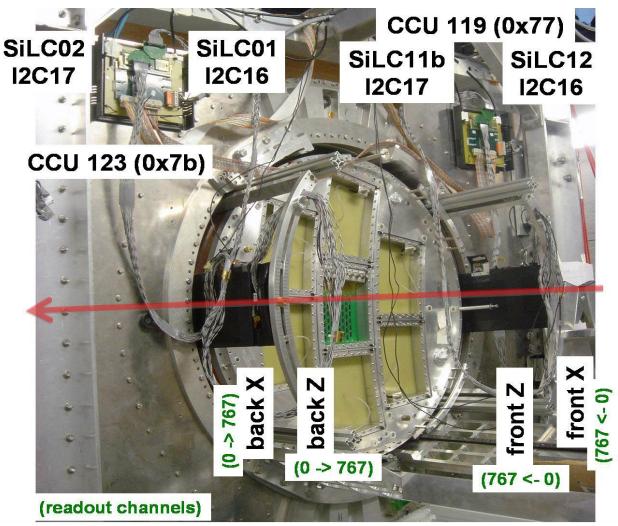








Geometry of the Silicon Sensors



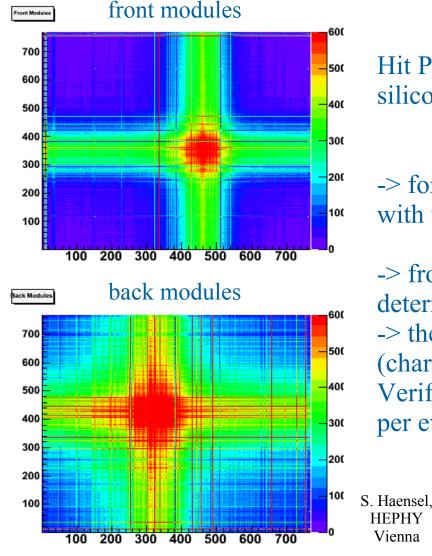
S. Haensel, HEPHY Vienna

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first look at the data

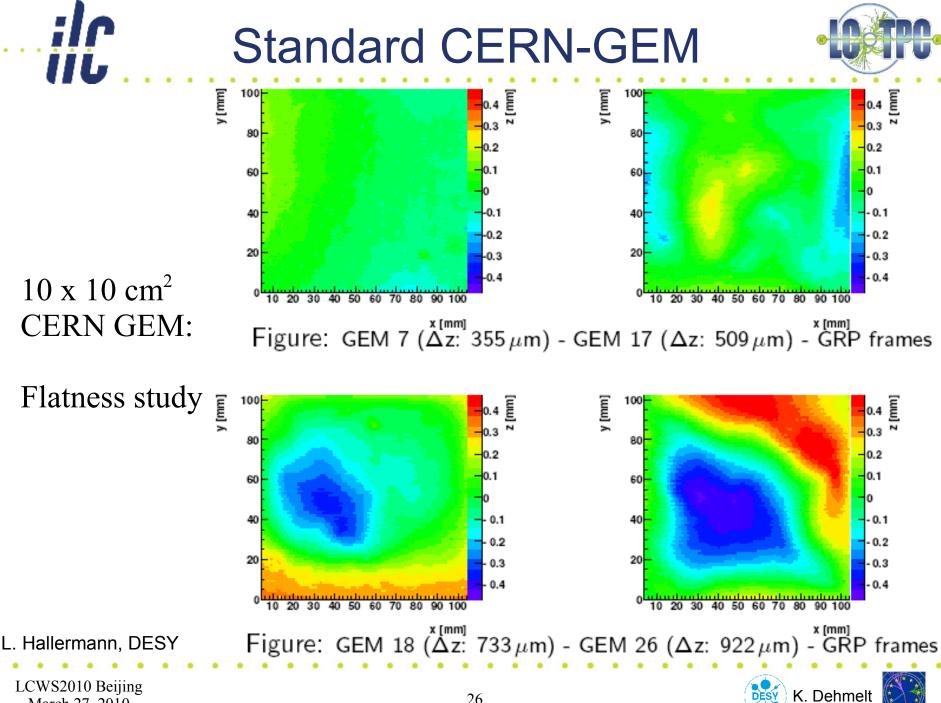
Hit Profile of the 768 strips (50 µm pitch) of the silicon strip sensors - Run 20075 (42434 events) x-axis = sensor which measures z y-axis = sensor which measures x -> for each cluster in the silicon sensors, the strip with the highest signal was counted

-> from the top plot the diameter of the beam can be determined to be about 5 mm -> the bottom plot shows that we get quite a lot of (charged) secondary particles Verified by looking at the mean number of clusters per event of the four silicon sensors:

front sensors ~ 1.4 clusters/events back sensors ~ 2.8 clusters/events



Vienna



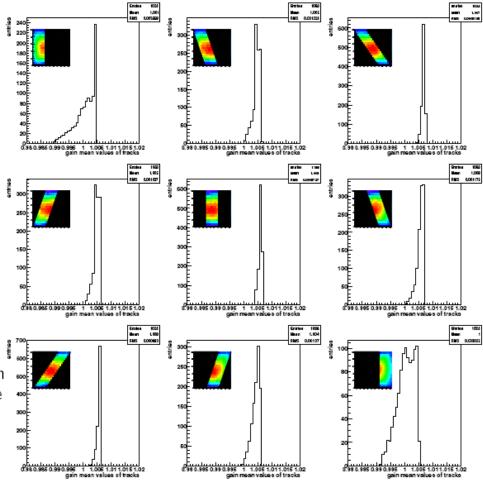
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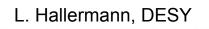


Standard CERN-GEM

region	mean value	RMS
left-left	1.001	0.36 %
left-mid	1.005	0.12%
left-right	1.007	0.05 %
mid-left	1.005	0.10%
mid-mid	1.006	0.06 %
mid-right	1.006	0.12%
right-left	1.006	0.07 %
right-mid	1.004	0.14%
right-right	1.000	0.30 %

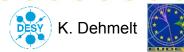
Table: Mean values and root mean squares of averaged track gains in different regions. The RMS represents the fluctuation of the effective gain corresponding to tracks within one region.





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LP DESY-GEM Module

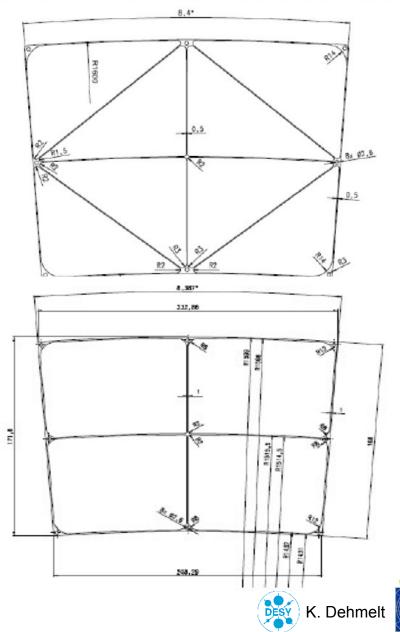


Design studies started

- Complete area coverage for LP module
- Standard CERN GEM:

 $d = 70 \ \mu m$ $p = 140 \ \mu m$

- 50 μm thick Kapton, each side covered with 5 μm Cu
- Ceramic frame
- Readout pads: (1.1 / 1.25) x (5.6 / 5.8) mm² 28 rows
- Gating GEM / wires optional
- S. Caiazzo, DESY





Summary & Outlook

 A Large Prototype of a TPC has been built and is being assembled/tested/commissioned by the LCTPC collaboration
 * Two MPGD technologies (with three electronics techniques) are being tested

- Infrastructure for Large Prototype has been constructed
- *e*⁻ test beam (DESY) in conjunction with PCMAG (*1T* magnet)
- Preliminary results are looking very promising
- Further test beam campaigns during this year:
 - Backplane integrated 10,000 channel readout system, based on ALTRO electronics → presently ongoing
 - Seven Micromegas modules with AFTER electronics attached to the modules
 - DESY GEM w/ ceramic grid





Summary & Outlook



	Large Prototype R&	D
Device	Lab(years)	Configuration
LP1	Desy(2007-2011)	Fieldcage $\oplus 2$ endplates:
		GEM+pixel, Micromegas+pixel
Purpose: Test constru	ction techniques using ~ 10000 Altro	or T2K channels
to demonstrate measure	ement of 6 GeV/c beam momentum	over 70cm tracklength,
including development	of correction procedures.	
LP1.5	Desy(2012)	$Fieldcage \oplus thinned endplate:$
		GEM+pixel, Micromegas+pixel
Purpose: Continue test	s using 10000 Altro or T2K channels	s to
demonstrate measurem	ent beam momentum over 70cm trac.	klength using LP1 thinned endplate.
If possible, test a jet-lik	ke environment.	
LP2	$FL^*C^*D^*O/AidaTBC$	Fieldcage⊕advanced-endcap prototype
	(after 2012)	GEM, Micromegas, or pixel
<u>Purpose:</u> Prototype for	LCTPC endcap module design: mec.	hanics, electronics, cooling,
power pulsing, gating.	Demonstrate measurement of high m	omentum.
Study (i	n approximate order of priority)	
	ue tests in electron beam to perfect corre	ction procedures
•Advance	ced endplate studies with max. 15% X0 is	ncluding cooling
•Powerp	oulsing/cooling tests using both LP and S	P
• Future	tests in hadron beam (if possible) for me	mentum resolution
and for p	performance in a jet environment	
		Micromoras
•Ion bac	kflow simulations of ion sheets for Gem,	micromegas
	kflow simulations of ion sheets for Gem, gn/test gating device	Micromegas
		K. Dehmelt



Summary & Outlook



	Large Prototype R&	D
Device	Lab(years)	Configuration
LP1	Desy(2007-2011)	$Fieldcage \oplus 2 endplates:$
		GEM+pixel, Micromegas+pixel
Purpose: Test	$construction techniques using \sim 10000 Altro$	or T2K channels
to demonstrate	e measurement of 6 GeV/c beam momentum	over 70cm tracklength,
including deve	lopment of correction procedures.	
LP1.5	Desy(2012)	Fieldcage⊕thinned endplate:
		GEM+pixel, Micromegas+pixel
Purpose: Cont	inue tests using 10000 Altro or T2K channels	s to
	neasurement beam momentum over 70cm track	
If possible, tes	t a jet-like environment.	
LP2	FL*C*D*O/AidaTBC	Fieldcage⊕advanced-endcap prototype:
	(after 2012)	GEM, Micromegas, or pixel
Purpose: Prote	otype for LCTPC endcap module design: mech	hanics, electronics, cooling,
power pulsing,	gating. Demonstrate measurement of high m	omentum.
	Study (in approximate order of priority)	
	•Continue tests in electron beam to perfect corre-	ction procedures
	•Advanced endplate studies with max. 15% X0 in	
	•Powerpulsing/cooling tests using both LP and S	P
	•Future tests in hadron beam (if possible) for mo	mentum resolution
	and for performance in a jet environment	
	•Ion backflow simulations of ion sheets for Gem,	Micromegas
	and design/test gating device	
2010 Beijing h 27, 2010	31	K. Dehmelt

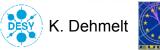


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Summary & Outlook



	Large Prototype 1	R&D
Device	Lab(years)	Configuration
LP1	Desy(2007-2011)	Fieldcage $\oplus 2$ endplates:
		GEM+pixel, Micromegas+pixel
Purpose: Test	construction techniques using ~ 10000 Ala	tro or T2K channels
to demonstrate	measurement of $6 \ GeV/c$ beam momentu	em over 70cm tracklength,
including develo	pment of correction procedures.	
LP1.5	Desy(2012)	Fieldcage⊕thinned endplate:
		GEM+pixel, Micromegas+pixel
Purpose: Contir	nue tests using 10000 Altro or T2K chans	nels to
demonstrate me	asurement beam momentum over 70cm t	racklength using LP1 thinned endplate.
If possible, test	a jet-like environment.	
LP2	FL*C*D*O/AidaTB	C Fieldcage⊕advanced-endcap prototype
	(after 2012)	GEM, Micromegas, or pixel
Purpose: Protot	ype for LCTPC endcap module design: n	nechanics, electronics, cooling,
power pulsing, g	pating. Demonstrate measurement of high	n momentum.
	Study (in approximate order of priority)	
	•Continue tests in electron beam to perfect co	prrection procedures
	•Advanced endplate studies with max. 15% X	-
	•Powerpulsing/cooling tests using both LP an	nd SP
	•Future tests in hadron beam (if possible) for	momentum resolution
	and for performance in a jet environment	
	• Ion backflow simulations of ion sheets for Ge	em, Micromegas
	and design/test gating device	
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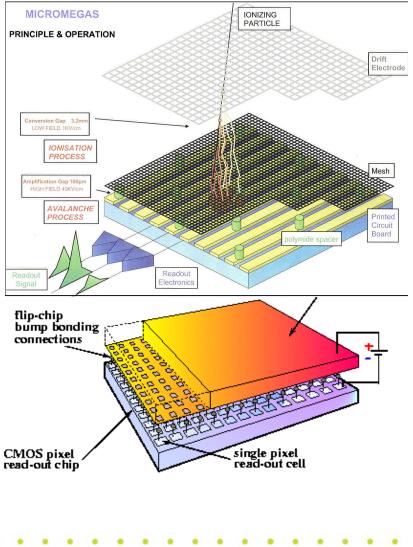




Backup Slides







High field created by Gas Gain GridsMost popular: GEM and Micromegas

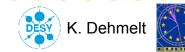
Use 'naked' CMOS pixel readout chip as anode

J. Timmermans NIKHEF

TimePix

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Three-fold readout electronics:

- <u>ALICE</u> based: new PCA16 amplifier chip + ALTRO chip (EUDET & LCTPC)
- <u>T2K</u> based: AFTER electronics for T2K TPC (CEA Saclay)
- <u>TDC</u> based: ASDQ chip + TDC (EUDET & Uni Rostock)

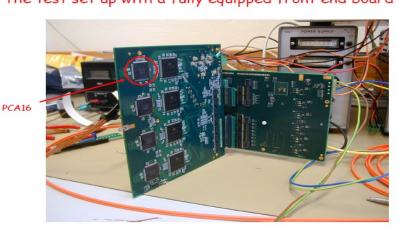
AFTER electronics for MicroMeGAS (resistive anode readout) ALTRO and TDC based electronics will be hooked to the GEM detector modules (connector compatibility)



Readout Electronics: ALTRO

PCA16:

1.5 V supply; power consumption <8 mW/channel 16 channel charge amplifier + anti-aliasing filter Fully differential output amplifier Programmable features signal polarity Power down mode (wake-up time = 1 ms) Peaking time (30 – 120 ns) Gain in 4 steps (12 – 27 mV/fC) Preamp out mode (bypass shaper or not) Tunable time constant of the preamplifier Basically pin-compatible with PASA



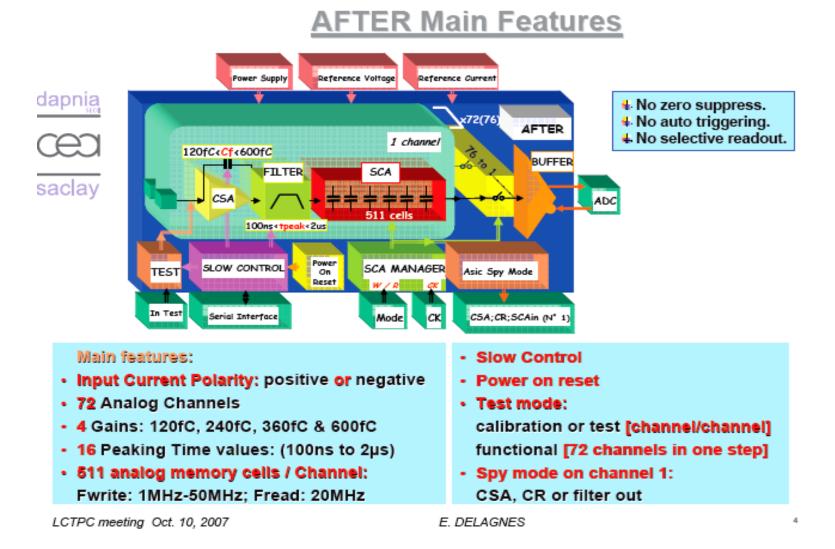
2048ch,16 FEC 1PC Data in/out 25cm 200MB/s 2 fibres close ethernet Dist 0MHz box Trigger +event # Trigger busy meters Other subsys dad Main away DAQ



The test set up with a fully equipped front end board

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Readout Electronics: AFTER



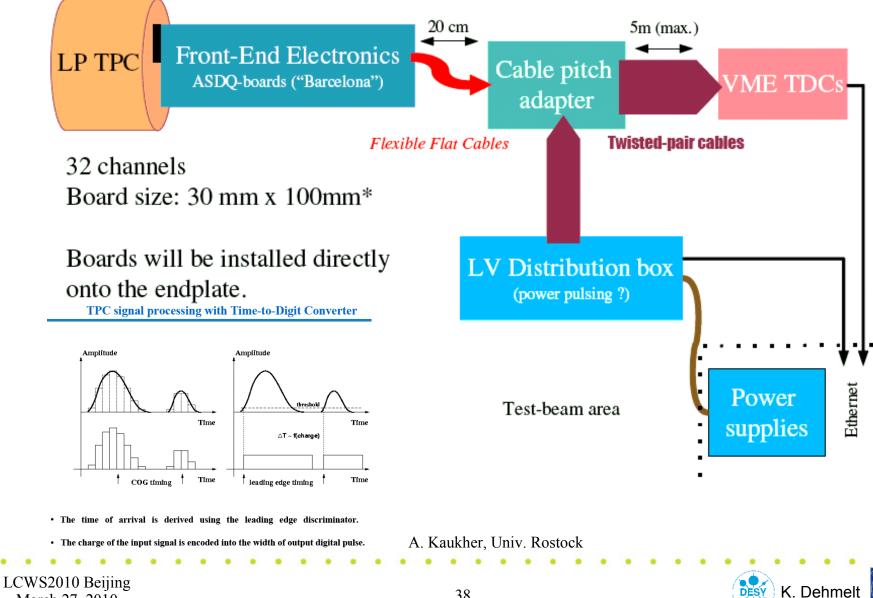
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Readout Electronics: TDC





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Standard CERN-GEM

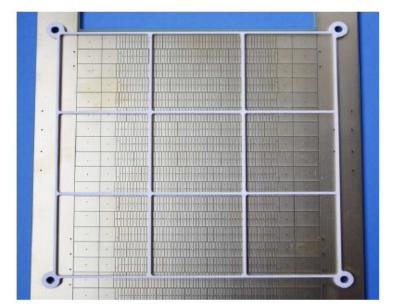
- triple grid GEM
- sensitive volume $10 \times 10 \times 66 \,\mathrm{cm^3}$
- pad size: 1,27 imes 7 mm²
- 12 rows, 48 pads
- cosmics
- 95% Argon, 5% CH₄
- magnetic field up to 4 T



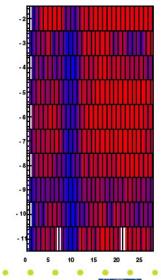
L. Hallermann, DESY

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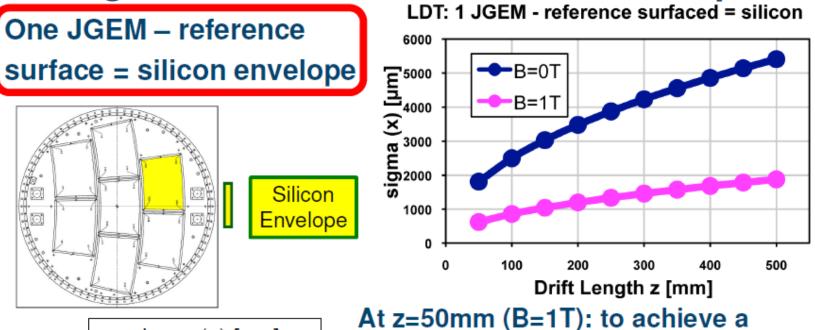








Alignment of TPC and Silicon Envelope



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	sigma (x) [µm]	
z [mm]	B=0T	B=1T
50	1813.286	622.096
100	2499.653	859.056
150	3031.417	1043.438

At z=50mm (B=1T): to achieve a resolution on the silicon plane of 2μm ~ 100000 and of 1μm ~ 400000 tracks are needed,

You must consider that only statistical errors are regarded!!!

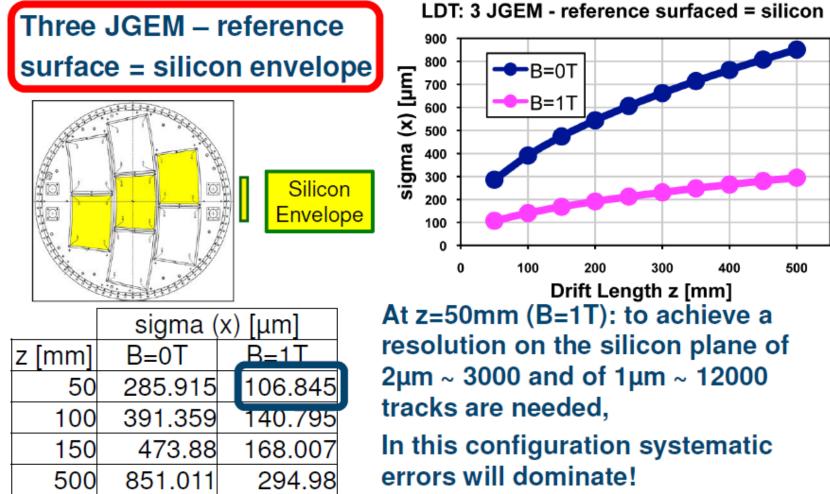
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Alignment of TPC and Silicon Envelope



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